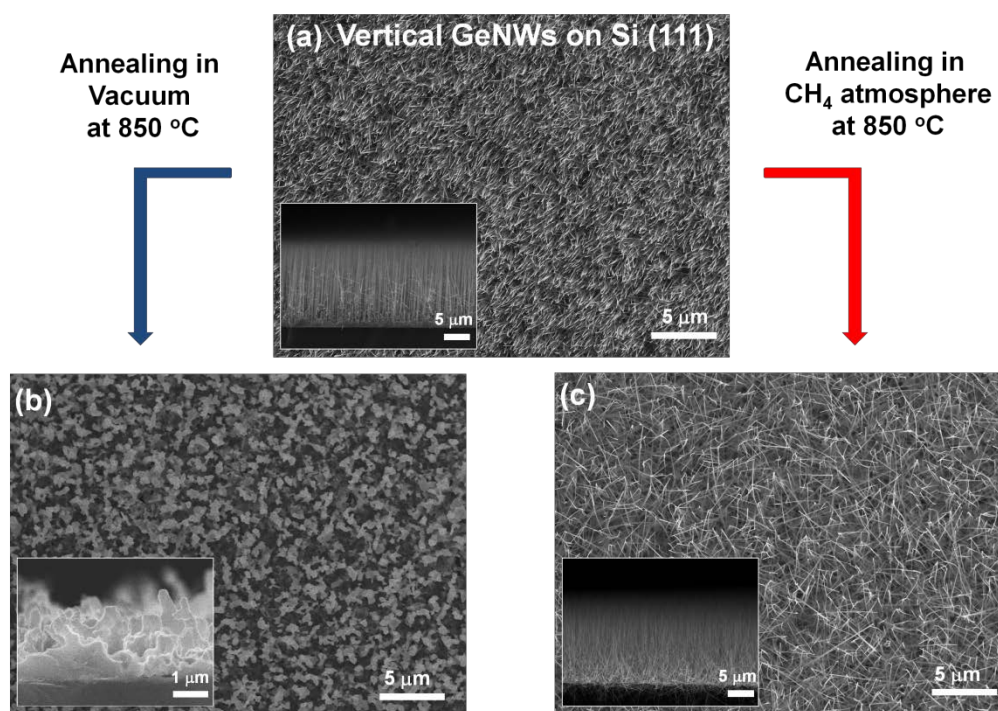


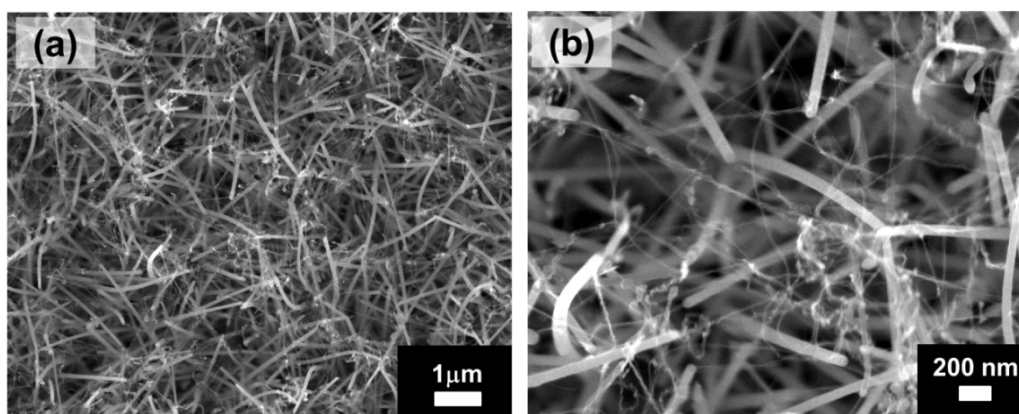
Supporting Information for

## Reliability Enhancement of Germanium Nanowires Using Graphene as a Protective Layer: Aspect of Thermal Stability

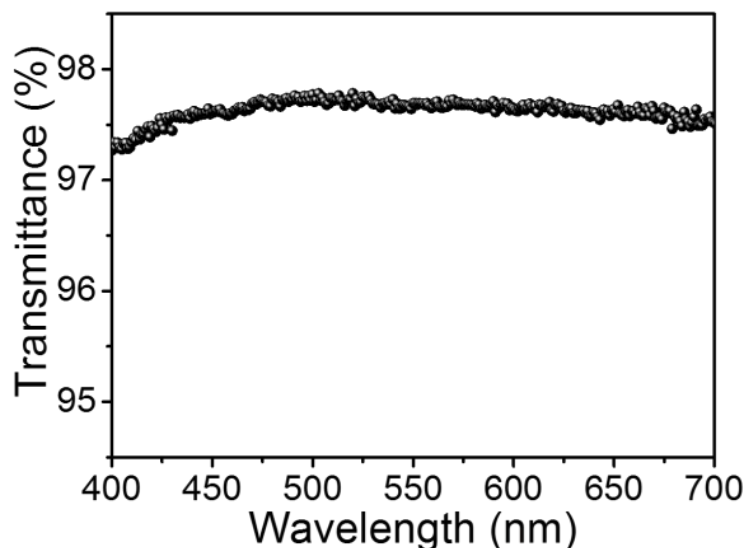
By J.-H. Lee, S.-H. Choi, S. P. Patole, Y. Jang, K. Heo, W.-J. Joo, J.-B. Yoo, S. W. Hwang and D. Whang\*



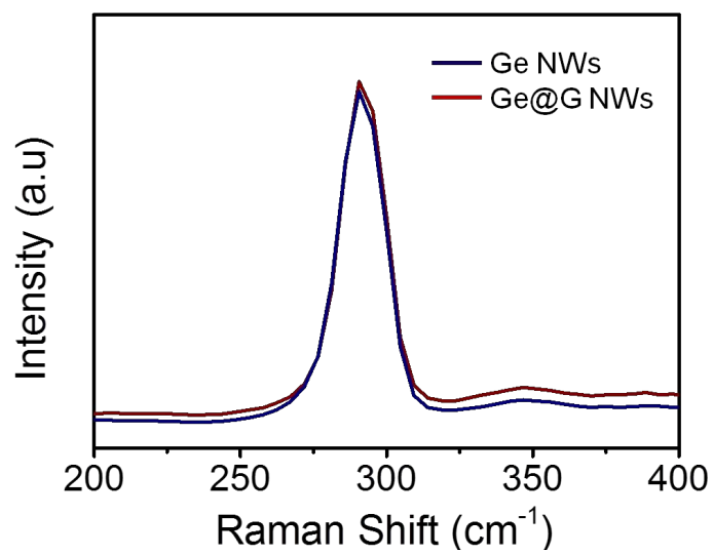
**Figure S1.** Graphene shell effects. Plan- and cross-sectional- SEM images of (a) vertically grown Ge NWs on Si (111); (b) thermal annealing of Ge NWs in vacuum for 5 min at 850 °C ; (c) thermal annealing of Ge NWs in CH<sub>4</sub> atmosphere for 5 min at 850 °C.



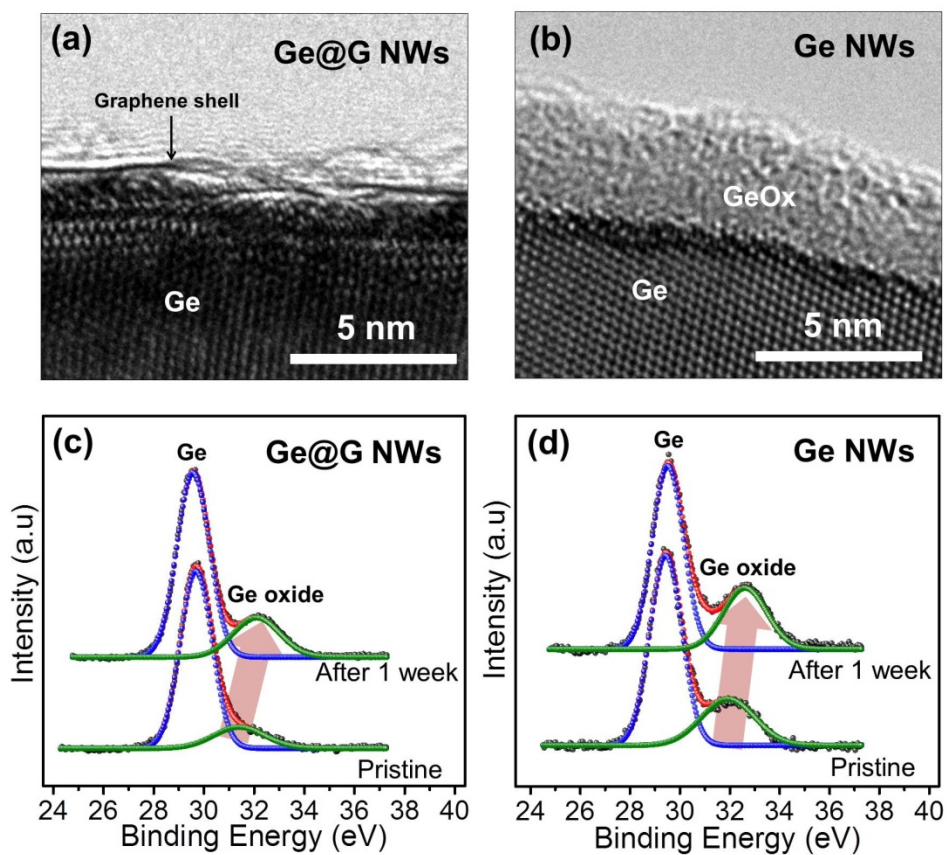
**Figure S2.** SEM image of Ge@G NWs grown at 900 °C.



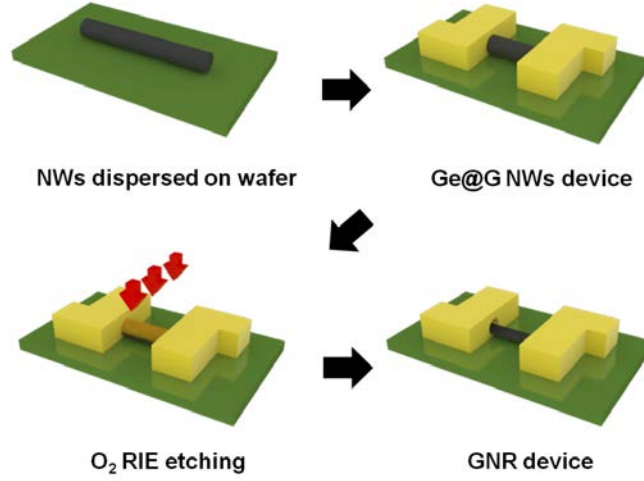
**Figure S3.** Transmittance of graphene film on quartz plate. Graphene was synthesized on the Ge substrate via a LPCVD technique, explained in experimental section. To transfer the as-grown graphene to the quartz plate, PMMA was used to prevent cracks during the transfer process and the sacrificial layer of Ge film was etched by  $\text{H}_2\text{O}_2/\text{HCl}/\text{BOE}$  mixture solution (Volume ratio of  $\text{H}_2\text{O}_2/\text{HCl}/\text{BOE}$  is 1:1:1).



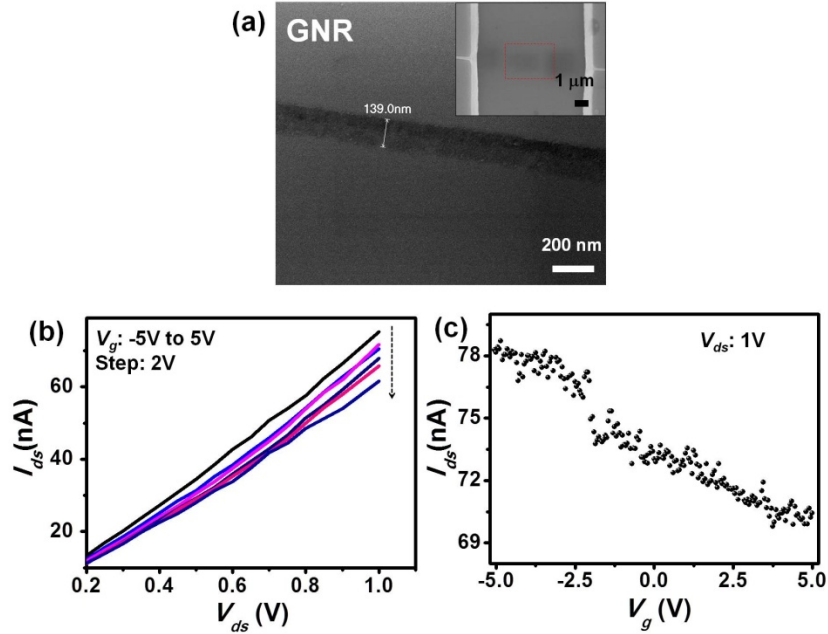
**Figure S4.** Raman spectra of Ge NWs and Ge@G NWs. From the FWHM of Ge NWs ( $\sim 19 \text{ cm}^{-1}$ ) and Ge@G NWs ( $\sim 20 \text{ cm}^{-1}$ ), crystallinity of Ge core is not affected by high growth temperature.



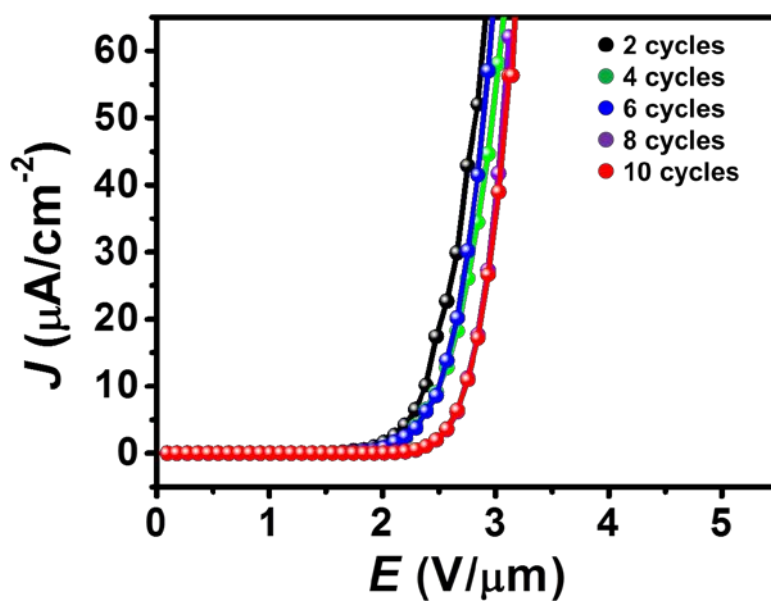
**Figure S5.** Oxidation behavior of Ge NWs and Ge@G NWs. TEM image of (a) Ge@G NWs and (b) Ge NWs after 1 week exposure in air. XPS spectra of (c) Ge@G NWs and (d) Ge NWs and after 1 week exposure in air.



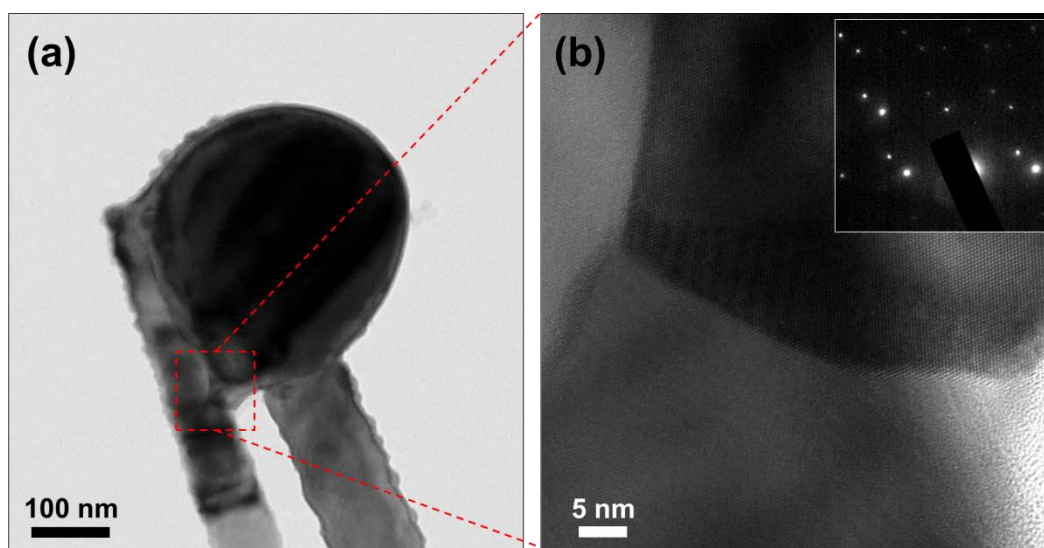
**Figure S6.** Schematic illustration of the fabrication of single-GNR devices. First, Ge@G NWs were deposited on a  $p^{++}$  (100) silicon wafer with 100 nm thick  $\text{SiO}_2$ . Then, the processes were performed of PR coating, prebaking, UV exposure, development (MF 300) and DI rinsing. Metal electrode material of 10 nm nichrome (NiCr, 80% Ni and 20% Cr) and 140 nm Au was deposited by a thermal evaporator. We used  $\text{O}_2$  plasma to etch the graphene shell except at the contact region between the NWs and the substrate. Exposed Ge was etched by pure DI water at 80 °C for 12h, leaving a single GNR.



**Figure S7.** Electrical properties of GNR device; (a) A SEM image of a single-GNR device; (b) current–voltage ( $I_{ds}$ – $V_{ds}$ ) characteristics at various  $V_g$ . (c) Transfer characteristics ( $I_{ds}$ – $V_g$ ) at  $V_{ds} = 1$  V. The GNR device exhibited p-type behavior with small on/off ratio ( $\sim 1.13$ ) because the width of GNR is not enough for bandgap opening.



**Figure S8.** Field emission results of Ge@G NWs. The average turn-on voltage is maintained at 2.25 V with small amount of fluctuation ( $\pm 0.19$  V)



**Figure S9.** (a-b) TEM images of pure GeNWs after 15 cycles of FE measurement. (Inset of (b)) SAED patterns of welded region of NWs.